

BASIC BLADE & BEAM SOCKET

(0.50 mm) .0197" PITCH • BSH SERIES



BSH
Mates:
BTB

BSH - **NO. OF POSITIONS PER ROW** - **01** - **PLATING OPTION** - **D** - **A** - **OTHER OPTION**

SPECIFICATIONS

Insulator Material:
Black LCP

Contact Material:
Phosphor Bronze

Plating:
Au or Sn over
50 μ " (1.27 μ m) Ni

Operating Temp Range:
-55 °C to +125 °C

Current Rating:
2 A per pin
(2 pins powered)

Voltage Rating:
175 VAC/247 VDC

Max Cycles:
100

PROCESSING

Lead-Free Solderable:
Yes

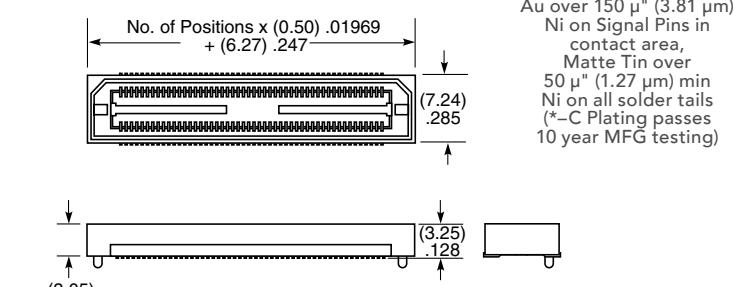
SMT Lead Coplanarity:
(0.10 mm) .004" max (030-090)
(0.15 mm) .006" max (120-150)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

Board Stacking:
For applications requiring more
than two connectors per board
or 90 positions or higher,
contact ipg@samtec.com

ALSO AVAILABLE

Contact Samtec

30 μ " (0.76 μ m) Gold
Edge Mount Capability
8 mm, 11 mm, 16 mm, 19 mm
and 22 mm Stack Height
(Caution: Some automatic
placement/inspection
machines may have
component height
restrictions. Please consult
machinery specifications.)
(11 mm, 16 mm, 19 mm
and 22 mm not available
with 50 positions)



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .197"

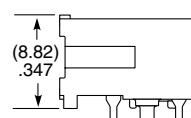
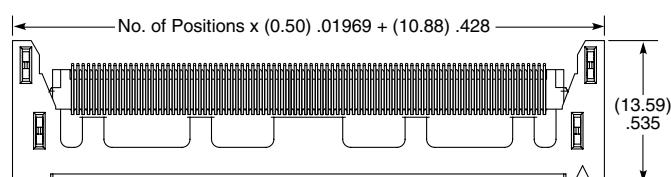
*Processing conditions
will affect mated height.

BSH - **NO. OF POSITIONS PER ROW** - **01** - **PLATING OPTION** - **D** - **RA** - **WT** - **OTHER OPTION**

-GP
= Guide Post

-F
= Gold Flash
on contact,
Matte Tin on tail

-L
= 10 μ " (0.25 μ m)
Gold on contact,
Matte Tin on tail



Note:

Some lengths, styles and
options are non-standard,
non-returnable.

